

Electronic Patent Application Fee Transmittal

Application Number:	10552370			
Filing Date:	26-Jul-2006			
Title of Invention:	Soap-molding die			
First Named Inventor/Applicant Name:	Takashi Nakano			
Filer:	Marvin Jay Spivak/Coursey Gordon			
Attorney Docket Number:	279330US3PCT			
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Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180